### SN55LVDS32, SN65LVDS32, SN65LVDS3486, SN65LVDS9637 HIGH-SPEED DIFFERENTIAL LINE RECEIVERS

SLLS262M - JULY 1997 - REVISED OCTOBER 2002

- Meet or Exceed the Requirements of ANSI TIA/EIA-644 Standard
- Operate With a Single 3.3-V Supply
- Designed for Signaling Rate of up to 400 Mbps
- Differential Input Thresholds ±100 mV Max
- Typical Propagation Delay Time of 2.1 ns
- Power Dissipation 60 mW Typical Per Receiver at 200 MHz
- Bus-Terminal ESD Protection Exceeds 8 kV
- Low-Voltage TTL (LVTTL) Logic Output Levels
- Pin Compatible With AM26LS32, MC3486, and μA9637
- Open-Circuit Fail Safe

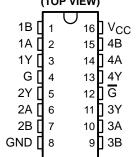
#### description

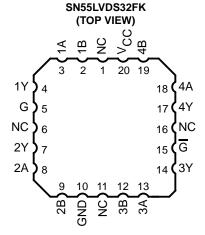
The SN55LVDS32, SN65LVDS32, SN65LVDS3486, and SN65LVDS9637 are differential line receivers that implement the electrical characteristics of low-voltage differential signaling (LVDS). This signaling technique lowers the output voltage levels of 5-V differential standard levels (such as EIA/TIA-422B) to reduce the power, increase the switching speeds, and allow operation with a 3.3-V supply rail. Any of the four differential receivers provides a valid logical output state with a ±100-mV differential input voltage within the input common-mode voltage range. The input common-mode voltage range allows 1 V of ground potential difference between two LVDS nodes.

The intended application of these devices and signaling technique is both point-to-point and multidrop (one driver and multiple receivers) data transmission over controlled impedance media of approximately  $100~\Omega$ . The transmission media may be printed-circuit board traces, backplanes, or cables. The ultimate rate and distance of data transfer depends on the attenuation characteristics of the media and the noise coupling to the environment.

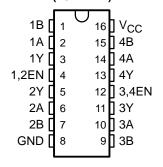
The SN65LVDS32, SN65LVDS3486, and SN65LVDS9637 are characterized for operation from -40°C to 85°C. The SN55LVDS32 is characterized for operation from -55°C to 125°C.

SN55LVDS32 ... J OR W SN65LVDS32 ... D OR PW (Marked as LVDS32 or 65LVDS32) (TOP VIEW)

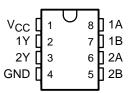




SN65LVDS3486D (Marked as LVDS3486) (TOP VIEW)



SN65LVDS9637D (Marked as DK637 or LVDS37) SN65LVDS9637DGN (Marked as L37) SN65LVDS9637DGK (Marked as AXF) (TOP VIEW)





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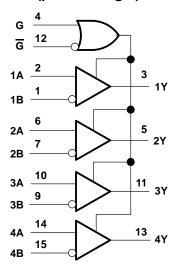
### SN55LVDS32, SN65LVDS32, SN65LVDS3486, SN65LVDS9637 HIGH-SPEED DIFFERENTIAL LINE RECEIVERS

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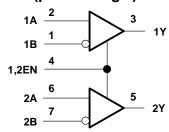
#### **AVAILABLE OPTIONS**

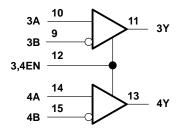
		PACKAGE						
TA	SMALL OUTLINE		MSOP	CHIP CARRIER	CERAMIC DIP	FLAT PACK		
	(D)	(PW)	WISOF	(FK)	(J)	(W)		
	SN65LVDS32D	SN65LVDS32PW	_		_	_		
–40°C to	SN65LVDS3486D		_		_	_		
85°C	SN65LVDS9637D		SN65LVDS9637DGN			_		
	_		SN65LVDS9637DGK			_		
–55°C to 125°C	_	_	_	SNJ55LVDS32FK	SNJ55LVDS32J	SNJ55LVDS32W SN55LVDS32W		

## 'LVDS32 logic diagram (positive logic)

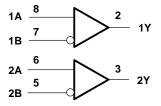


# SN65LVDS3486D logic diagram (positive logic)





## SN65LVDS9637D logic diagram (positive logic)



## FUNCTION TABLE SN55LVDS32, SN65LVDS32

DIFFERENTIAL INPUT	ENA	BLES	OUTPUT
A, B	G	G	Υ
V <sub>ID</sub> ≥ 100 mV	H X	X L	H H
-100 mV < V <sub>ID</sub> < 100 mV	H X	X L	?
$V_{ID} \le -100 \text{ mV}$	H X	X L	L L
Х	L	Н	Z
Open	H X	X L	H

H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

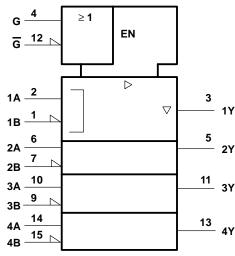
#### FUNCTION TABLE SN65LVDS3486

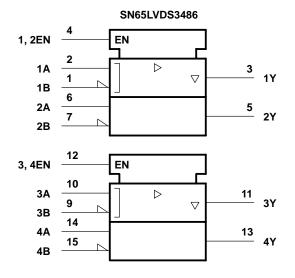
DIFFERENTIAL INPUT A, B	ENABLE EN	OUTPUT Y
V <sub>ID</sub> ≥ 100 mV	Н	Н
-100 mV < V <sub>ID</sub> < 100 mV	Н	?
V <sub>ID</sub> ≤ −100 mV	Н	L
Х	L	Z
Open	Н	Н

H = high level, L = low level, X = irrelevant, Z = high impedance (off), ? = indeterminate

### logic symbols†

## SN55LVDS32, SN65LVDS32





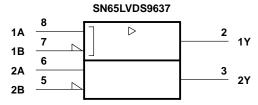
<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## FUNCTION TABLE SN65LVDS9637

DIFFERENTIAL INPUT A, B	OUTPUT Y
$V_{ID} \ge 100 \text{ mV}$	Н
-100 mV < V <sub>ID</sub> < 100 mV	?
$V_{ID} \le -100 \text{ mV}$	L
Open	Н

H = high level, L = low level, ? = indeterminate

### logic symbol†



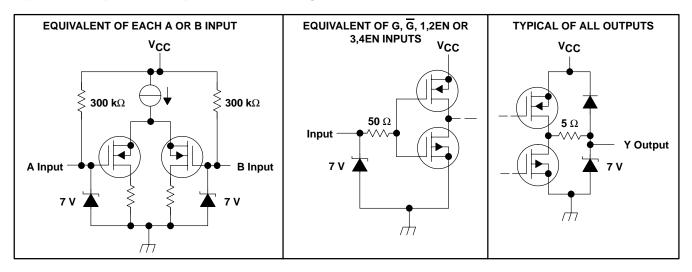
<sup>†</sup>This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



### SN55LVDS32, SN65LVDS32, SN65LVDS3486, SN65LVDS9637 HIGH-SPEED DIFFERENTIAL LINE RECEIVERS

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#### equivalent input and output schematic diagrams



### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V <sub>CC</sub> (see Note 1)	0.5 V to 4 V
Input voltage range, V <sub>I</sub> (enables and output)	$\dots$ -0.5 V to V <sub>CC</sub> + 0.5 V
Input voltage range, V <sub>I</sub> (A or B)	
Continuous total power dissipation	See Dissipation Rating Table
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T <sub>stq</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages, except differential I/O bus voltages, are with respect to the network ground terminal.

#### **DISSIPATION RATING TABLE**

PACKAGE	$\begin{aligned} & \textbf{T}_{\pmb{A}} \leq \textbf{25}^{\circ} \textbf{C} \\ & \textbf{POWER RATING} \end{aligned}$	DERATING FACTOR <sup>‡</sup> ABOVE T <sub>A</sub> = 25°C	T <sub>A</sub> = 70°C POWER RATING	T <sub>A</sub> = 85°C POWER RATING	T <sub>A</sub> = 125°C POWER RATING
D (8)	725 mW	5.8 mW/°C	464 mW	377 mW	_
D (16)	950 mW	7.6 mW/°C	608 mW	494 mW	_
DGK	425 mW	3.4 mW/°C	272 mW	221 mW	_
DGN	2.14 W	17.1 mW/°C	1.37 W	1.11 W	_
FK	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW
J	1375 mW	11.0 mW/°C	880 mW	715 mW	275 mW
PW (16)	774 mW	6.2 mW/°C	496 mW	402 mW	_
W	1000 mW	8.0 mW/°C	640 mW	520 mW	200 mW

<sup>‡</sup> This is the inverse of the junction-to-ambient thermal resistance when board mounted and with no air flow.

### recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V <sub>CC</sub>		3	3.3	3.6	V
High-level input voltage, V <sub>IH</sub>	G, G, 1,2EN, or 3,4EN	2			V
Low-level input voltage, V <sub>IL</sub>	G, G, 1,2EN, or 3,4EN			0.8	V
Magnitude of differential input voltage,  V <sub>ID</sub>		0.1		0.6	V
Common-mode input voltage, V <sub>IC</sub> (see Figure 1)		$\frac{ V_{\text{ID}} }{2}$	2.4 -	$\frac{ V_{ID} }{2}$	V
			VC	S-0.8	
Operating free-air temperature, T <sub>Δ</sub>	SN65 prefix	-40		85	°C
Operating nee-all temperature, 1A	SN55 prefix	-55		125	)

## COMMON-MODE INPUT VOLTAGE RANGE

### DIFFERENTIAL INPUT VOLTAGE

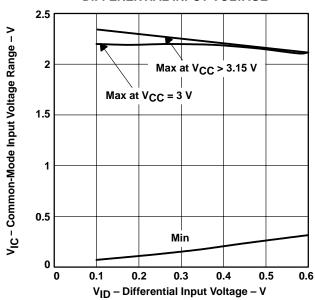


Figure 1.  $V_{\mbox{\scriptsize IC}}$  Versus  $V_{\mbox{\scriptsize ID}}$  and  $V_{\mbox{\scriptsize CC}}$ 

### SN55LVDS32, SN65LVDS32, SN65LVDS3486, SN65LVDS9637 HIGH-SPEED DIFFERENTIAL LINE RECEIVERS

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## SN55LVDS32 electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP <sup>†</sup>	MAX	UNIT
VITH+	Positive-going differential input voltage threshold	See Figure 2, Table 1, and Note	2		100	mV
V <sub>ITH</sub> _	Negative-going differential input voltage threshold‡	See Figure 2, Table 1, and Note	2 –100			mV
Vон	High-level output voltage	$I_{OH} = -8 \text{ mA}$	2.4			V
VOL	Low-level output voltage	$I_{OL} = 8 \text{ mA}$			0.4	V
	Supply current	Enabled, No load		10	18	mA
'cc	Supply current	Disabled		0.25	0.5	IIIA
1.	Input current (A or B inputs)	V <sub>I</sub> = 0	-2	-10	-20	
'	input current (A or B inputs)	V <sub>I</sub> = 2.4 V	-1.2	-3		μА
I <sub>I</sub> (OFF)	Power-off input current (A or B inputs)	$V_{CC} = 0,$ $V_{I} = 2.4$	/	6	20	μΑ
lН	High-level input current (EN, G, or G inputs)	V <sub>IH</sub> = 2 V			10	μΑ
I <sub>Ι</sub> L	Low-level input current (EN, G, or G inputs)	V <sub>IL</sub> = 0.8 V			10	μΑ
loz	High-impedance output current	VO = 0 or $VCC$			±12	μΑ

<sup>&</sup>lt;sup>†</sup> All typical values are at  $T_A = 25$ °C and with  $V_{CC} = 3.3$  V.

NOTE 2:  $|V_{ITH}| = 200 \text{ mV}$  for operation at  $-55^{\circ}\text{C}$ 

## SN55LVDS32 switching characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low-to-high-level output		1.3	2.3	6	ns
tPHL	Propagation delay time, high-to-low-level output		1.4	2.2	6.1	ns
t <sub>sk(o)</sub>	Channel-to-channel output skew§	C <sub>L</sub> = 10 pF, See Figure 3		0.1		ns
t <sub>r</sub>	Output signal rise time, 20% to 80%			0.6		ns
tf	Output signal fall time, 80% to 20%			0.7		ns
<sup>t</sup> PHZ	Propagation delay time, high-level-to-high-impedance output			6.5	12	ns
t <sub>PLZ</sub>	Propagation delay time, low-level-to-high-impedance output	See Figure 4		5.5	12	ns
<sup>t</sup> PZH	Propagation delay time, high-impedance-to-high-level output	See Figure 4		8	14	ns
tPZL	Propagation delay time, high-impedance-to-low-level output			3	12	ns

 $<sup>\</sup>S_{t_{Sk(0)}}$  is the maximum delay time difference between drivers on the same device.

<sup>&</sup>lt;sup>‡</sup> The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for the negative-going differential input voltage threshold only.

#### SN65LVDSxxxx electrical characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN65LVDS32 SN65LVDS3486 SN65LVDS9637			UNIT	
					MIN	TYP†	MAX	
V <sub>IT+</sub>	Positive-going differential input voltage thres	hold	See Figure 2	and Table 1			100	mV
VIT-	Negative-going differential input voltage thre	shold <sup>‡</sup>	See Figure 2	and Table 1	-100			mV
V	High level output voltage		$I_{OH} = -8 \text{ mA}$		2.4			V
VOH	OH High-level output voltage		$I_{OH} = -4 \text{ mA}$		2.8			V
VOL	Low-level output voltage	Low-level output voltage I <sub>OL</sub> = 8 mA				0.4	V	
		SN65LVDS32,	Enabled,	No load		10	18	
Icc	Supply current	SN65LVDS3486	Disabled			0.25	0.5	mA
		SN65LVDS9637	No load			5.5	10	
1.	Innut ourrent (A or D innute)		V <sub>I</sub> = 0		-2	-10	-20	^
11	Input current (A or B inputs)		V <sub>I</sub> = 2.4 V		-1.2	-3		μΑ
I <sub>I</sub> (OFF)	Power-off input current (A or B inputs)		$V_{CC} = 0$ ,	V <sub>I</sub> = 3.6 V		6	20	μΑ
		V <sub>IH</sub> = 2 V				10	μΑ	
I <sub>IL</sub> Low-level input current (EN, G, or $\overline{G}$ inputs)		V <sub>IL</sub> = 0.8 V				10	μΑ	
I <sub>OZ</sub>	High-impedance output current		$V_O = 0$ or $V_C$	С			±10	μΑ

<sup>&</sup>lt;sup>†</sup> All typical values are at  $T_A = 25^{\circ}$ C and with  $V_{CC} = 3.3$  V.

#### SN65LVDSxxxx switching characteristics over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	SN65LVDS32 SN65LVDS3486 SN65LVDS9637			UNIT
			MIN	TYP	MAX	
tPLH	Propagation delay time, low-to-high-level output		1.5	2.1	3	ns
tPHL	Propagation delay time, high-to-low-level output		1.5	2.1	3	ns
t <sub>sk(p)</sub>	Pulse skew ( tpHL - tpLH )			0	0.4	ns
t <sub>sk(o)</sub>	Channel-to-channel output skew§	C <sub>L</sub> = 10 pF, See Figure 3		0.1	0.3	ns
t <sub>sk(pp)</sub>	Part-to-part skew¶				1	ns
t <sub>r</sub>	Output signal rise time, 20% to 80%			0.6		ns
tf	Output signal fall time, 80% to 20%			0.7		ns
tPHZ	Propagation delay time, high-level-to-high-impedance output			6.5	12	ns
tPLZ	Propagation delay time, low-level-to-high-impedance output	Soo Eiguro 4		5.5	12	ns
<sup>t</sup> PZH	Propagation delay time, high-impedance-to-high-level output	See Figure 4 8		12	ns	
t <sub>PZL</sub>	Propagation delay time, high-impedance-to-low-level output			3	12	ns

<sup>§</sup> t<sub>Sk(0)</sub> is the skew between specified outputs of a single device with all driving inputs connected together and the outputs switching in the same direction while driving identical specified loads.

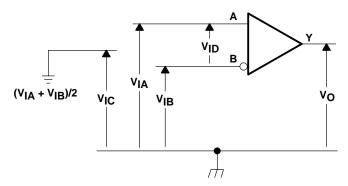
¶ t<sub>sk(pp)</sub> is the magnitude of the difference in propagation delay times between any specified terminals of two devices when both devices operate



<sup>‡</sup> The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for the negative-going differential input voltage threshold only.

with the same supply voltages, same temperature, and have identical packages and test circuits.

#### PARAMETER MEASUREMENT INFORMATION

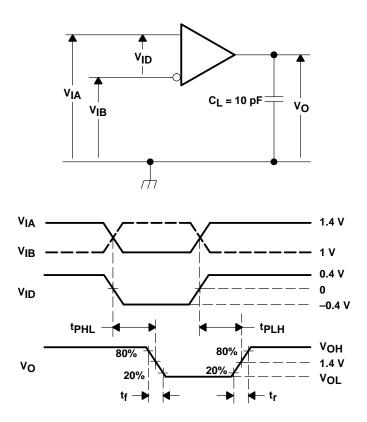


**Figure 2. Voltage Definitions** 

Table 1. Receiver Minimum and Maximum Input Threshold Test Voltages

	LIED AGES	RESULTING DIFFERENTIAL INPUT VOLTAGE	RESULTING COMMON-MODE INPUT VOLTAGE
V <sub>IA</sub> (V)	V <sub>IB</sub> (V)	V <sub>ID</sub> (mV)	V <sub>IC</sub> (V)
1.25	1.15	100	1.2
1.15	1.25	-100	1.2
2.4	2.3	100	2.35
2.3	2.4	-100	2.35
0.1	0	100	0.05
0	0.1	-100	0.05
1.5	0.9	600	1.2
0.9	1.5	-600	1.2
2.4	1.8	600	2.1
1.8	2.4	-600	2.1
0.6	0	600	0.3
0	0.6	-600	0.3

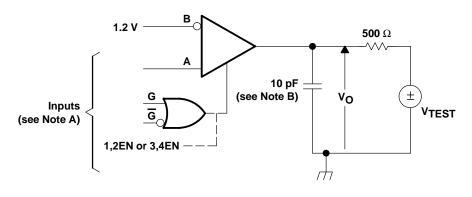
#### PARAMETER MEASUREMENT INFORMATION

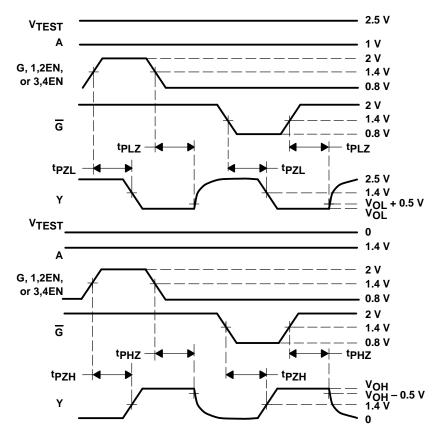


- NOTES: A. All input pulses are supplied by a generator having the following characteristics:  $t_{\Gamma}$  or  $t_{\tilde{f}} \leq 1$  ns, pulse repetition rate (PRR) = 50 Mpps, pulse width =  $10 \pm 0.2$  ns.
  - B. C<sub>L</sub> includes instrumentation and fixture capacitance within 6 mm of the D.U.T.

Figure 3. Timing Test Circuit and Waveforms

#### PARAMETER MEASUREMENT INFORMATION

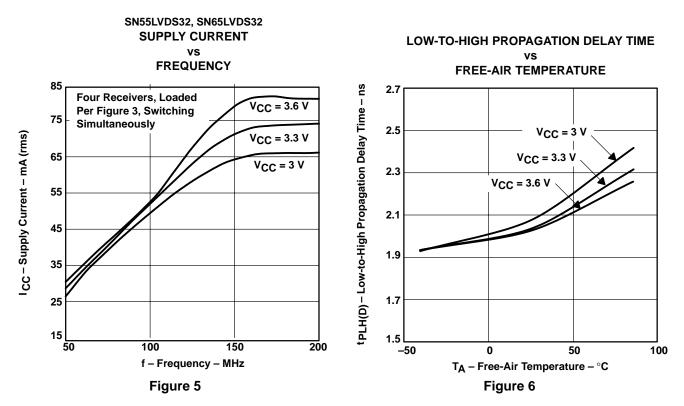




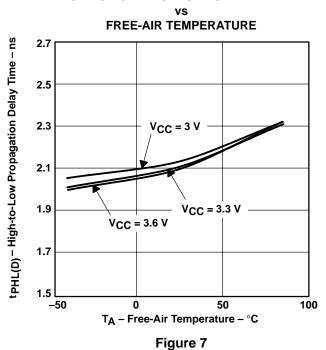
- NOTES: A. All input pulses are supplied by a generator having the following characteristics:  $t_{\Gamma}$  or  $t_{\tilde{f}} \leq 1$  ns, pulse repetition rate (PRR) = 0.5 Mpps, pulse width = 500  $\pm$  10 ns.
  - B. C<sub>L</sub> includes instrumentation and fixture capacitance within 6 mm of the D.U.T.

Figure 4. Enable- and Disable-Time Test Circuit and Waveforms

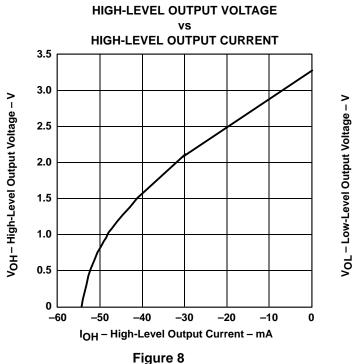
#### TYPICAL CHARACTERISTICS

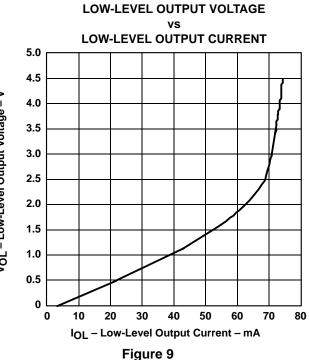


#### **HIGH-TO-LOW PROPAGATION DELAY TIME**



#### **TYPICAL CHARACTERISTICS**





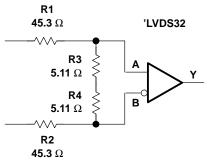
#### **APPLICATION INFORMATION**

#### using an LVDS receiver with RS-422 data

Receipt of data from a TIA/EIA-422 line driver may be accomplished using a TIA/EIA-644 line receiver with the addition of an attenuator circuit. This technique gives the user a very high-speed and low-power 422 receiver.

If the ground noise between the transmitter and receiver is not a concern (less than  $\pm 1$  V), the answer can be as simple as shown in Figure 10. A resistor divider circuit in front of the LVDS receiver attenuates the 422 differential signal to LVDS levels.

The resistors present a total differential load of  $100\,\Omega$  to match the characteristic impedance of the transmission line and to reduce the signal 10:1. The maximum 422 differential output signal, or 6 V, is reduced to 600 mV. The high input impedance of the LVDS receiver prevents input bias offsets and maintains a greater than 200-mV differential input voltage threshold at the inputs to the divider. This circuit is used in front of each LVDS channel that also receives 422 signals.



NOTE A: The components used were standard values.

R1, R2 = NRC12F45R3TR, NIC components, 45.3  $\Omega$ , 1/8 W, 1%, 1206 package R3, R4 = NRC12F5R11TR, NIC components, 5.11  $\Omega$ , 1/8 W, 1%, 1206 package

The resistor values do not need to be 1% tolerance. However, it can be difficult locating a supplier of resistors having values less than  $100~\Omega$  in stock and readily available. The user may find other suppliers with comparable parts having tolerances of 5% or even 10%. These parts are adequate for use in this circuit.

Figure 10. RS-422 Data Input to an LVDS Receiver Under Low Ground-Noise Conditions

If ground noise between the RS-422 driver and LVDS receiver is a concern, the common-mode voltage must be attenuated. The circuit must then be modified to connect the node between R3 and R4 to the LVDS receiver ground. This modification to the circuit increases the common-mode voltage from  $\pm 1$  V to greater than  $\pm 4.5$  V.

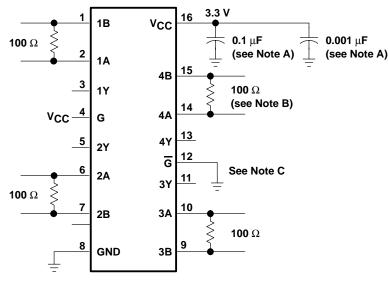
#### APPLICATION INFORMATION

The devices are generally used as building blocks for high-speed point-to-point data transmission where ground differences are less than 1 V. Devices can interoperate with RS-422, PECL, and IEEE-P1596. Drivers/receivers approach ECL speeds without the power and dual-supply requirements.

## TRANSMISSION DISTANCE SIGNALING RATE 100 30% Jitter Fransmission Distance – m (see Note A) 10 5% Jitter (see Note A) 24 AWG UTP 96 $\Omega$ (PVC Dielectric) 0.1 10 100 1000 Signaling Rate - Mbps

NOTE A: This parameter is the percentage of distortion of the unit interval (UI) with a pseudorandom data pattern.

Figure 11. Typical Transmission Distance Versus Signaling Rate



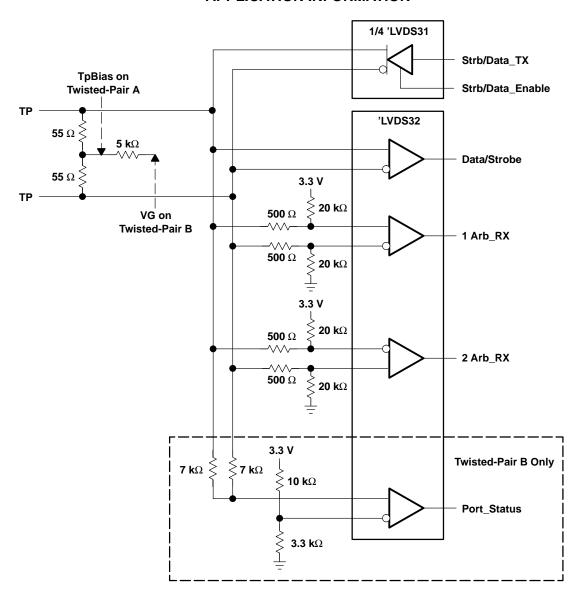
NOTES: A. Place a 0.1-μF and a 0.001-μF Z5U ceramic, mica, or polystyrene dielectric, 0805 size, chip capacitor between V<sub>CC</sub> and the ground plane. The capacitors should be located as close as possible to the device terminals.

- B. The termination resistance value should match the nominal characteristic impedance of the transmission media with ±10%.
- C. Unused enable inputs should be tied to V<sub>CC</sub> or GND as appropriate.

Figure 12. Typical Application Circuit Schematic



#### **APPLICATION INFORMATION**



NOTES: A. Resistors are leadless, thick film (0603), 5% tolerance.

- B. Decoupling capacitance is not shown but recommended.
- C. V<sub>CC</sub> is 3 V to 3.6 V.
- D. The differential output voltage of the 'LVDS31 can exceed that allowed by IEEE1394.

Figure 13. 100-Mbps IEEE 1394 Transceiver

#### APPLICATION INFORMATION

#### fail safe

One of the most common problems with differential signaling applications is how the system responds when no differential voltage is present on the signal pair. The LVDS receiver is like most differential line receivers in that its output logic state can be indeterminate when the differential input voltage is between –100 mV and 100 mV if it is within its recommended input common-mode voltage range. However, TI LVDS receivers handle the open-input circuit situation differently.

Open-circuit means that there is little or no input current to the receiver from the data line itself. This could be when the driver is in a high-impedance state or the cable is disconnected. When this occurs, the LVDS receiver pulls each line of the signal pair to near  $V_{CC}$  through 300-k $\Omega$  resistors (see Figure 14). The fail-safe feature uses an AND gate with input voltage thresholds at about 2.3 V to detect this condition and force the output to a high level, regardless of the differential input voltage.

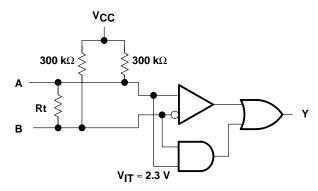
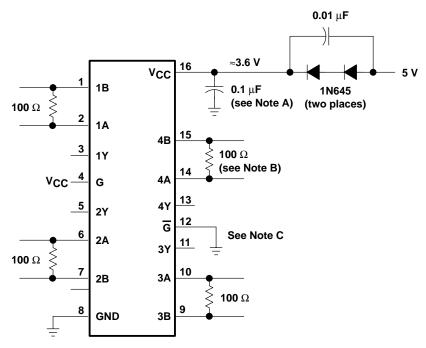


Figure 14. Open-Circuit Fail Safe of LVDS Receiver

It is only under these conditions that the output of the receiver is valid with less than a 100-mV differential input voltage magnitude. The presence of the termination resistor, Rt, does not affect the fail-safe function as long as it is connected as shown in Figure 14. Other termination circuits may allow a dc current to ground that could defeat the pullup currents from the receiver and the fail-safe feature.

#### **APPLICATION INFORMATION**



- NOTES: A. Place a 0.1-μF Z5U ceramic, mica, or polystyrene dielectric, 0805 size, chip capacitor between V<sub>CC</sub> and the ground plane. The capacitor should be located as close as possible to the device terminals.
  - B. The termination resistance value should match the nominal characteristic impedance of the transmission media with ±10%.
  - C. Unused enable inputs should be tied to  $V_{CC}$  or GND, as appropriate.

Figure 15. Operation With 5-V Supply

#### related information

IBIS modeling is available for this device. Please contact the local TI sales office or the TI Web site at www.ti.com for more information.

For more application guidelines, please see the following documents:

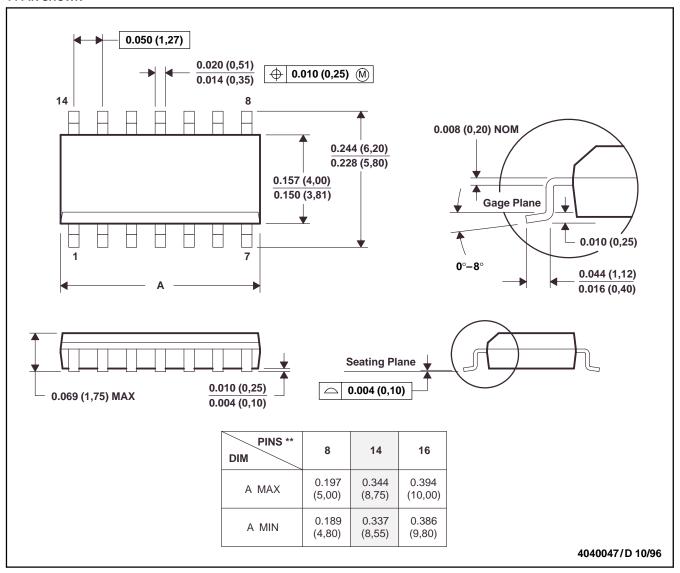
- Low-Voltage Differential Signaling Design Notes (literature number SLLA014)
- Interface Circuits for TIA/EIA-644 (LVDS) (literature number SLLA038)
- Reducing EMI With LVDS (literature number SLLA030)
- Slew Rate Control of LVDS Circuits (literature number SLLA034)
- Using an LVDS Receiver With RS-422 Data (literature number SLLA031)
- Evaluating the LVDS EVM (literature number SLLA033)

#### **MECHANICAL INFORMATION**

#### D (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE

#### 14 PIN SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

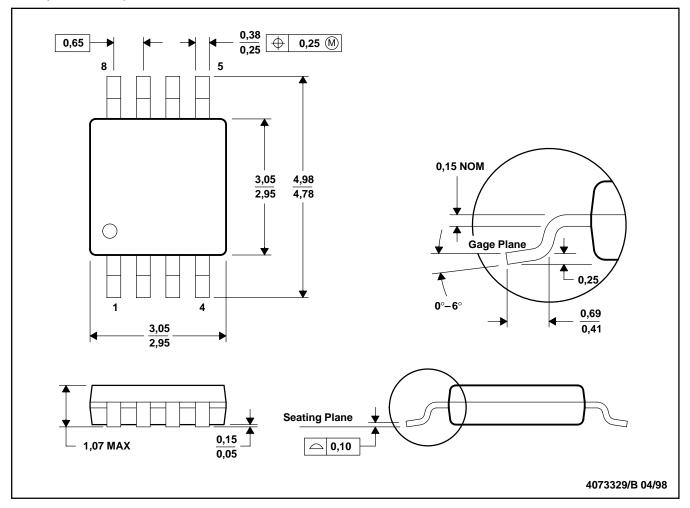
C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012

#### **MECHANICAL INFORMATION**

#### DGK (R-PDSO-G8)

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

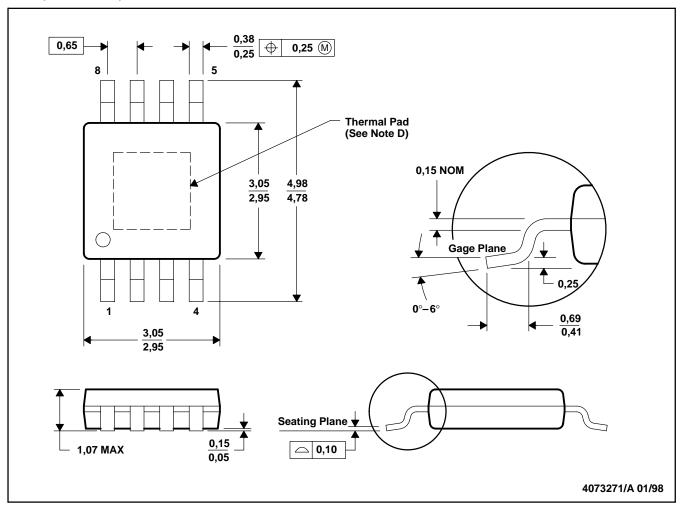
C. Body dimensions do not include mold flash or protrusion.

D. Falls within JEDEC MO-187

#### **MECHANICAL INFORMATION**

#### DGN (S-PDSO-G8)

#### PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions include mold flash or protrusions.
- D. The package thermal performance may be enhanced by attaching an external heat sink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
- E. Falls within JEDEC MO-187

PowerPAD is a trademark of Texas Instruments.

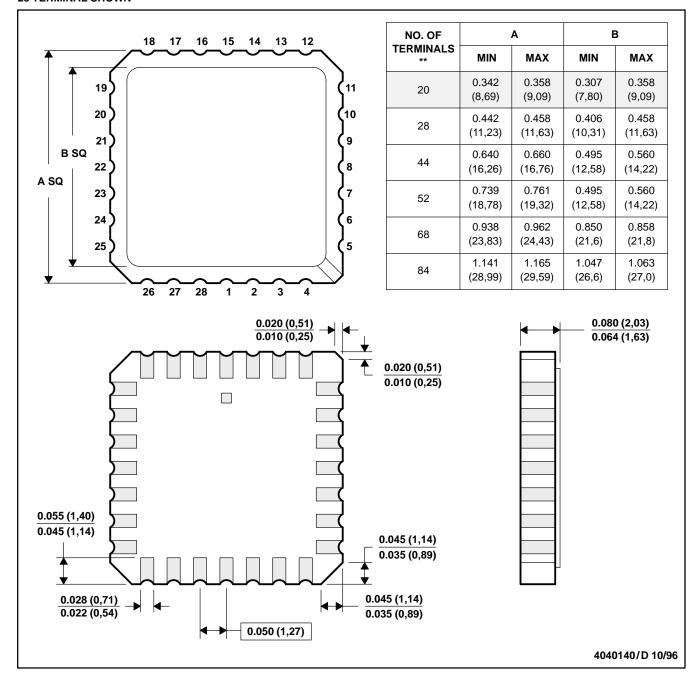


#### **MECHANICAL INFORMATION**

#### FK (S-CQCC-N\*\*)

#### 28 TERMINAL SHOWN

#### **LEADLESS CERAMIC CHIP CARRIER**



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a metal lid.
  - D. The terminals are gold plated.
  - E. Falls within JEDEC MS-004

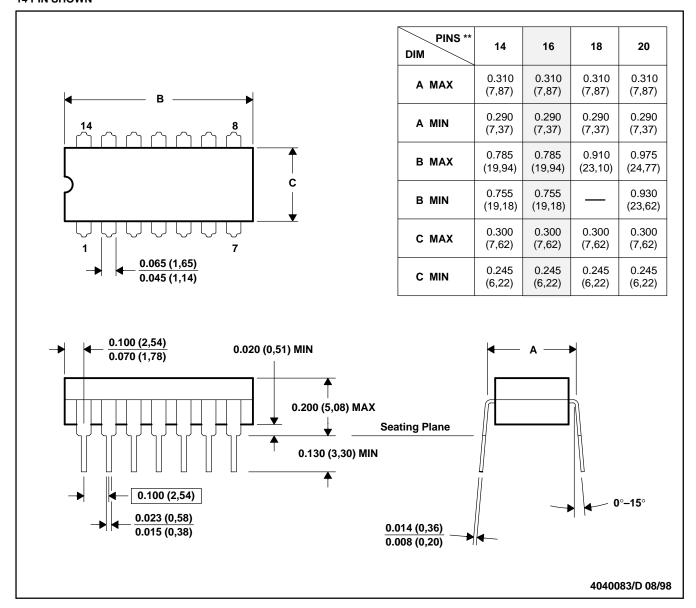


#### **MECHANICAL INFORMATION**

#### J (R-GDIP-T\*\*)

#### **CERAMIC DUAL-IN-LINE PACKAGE**

## 14 PIN SHOWN

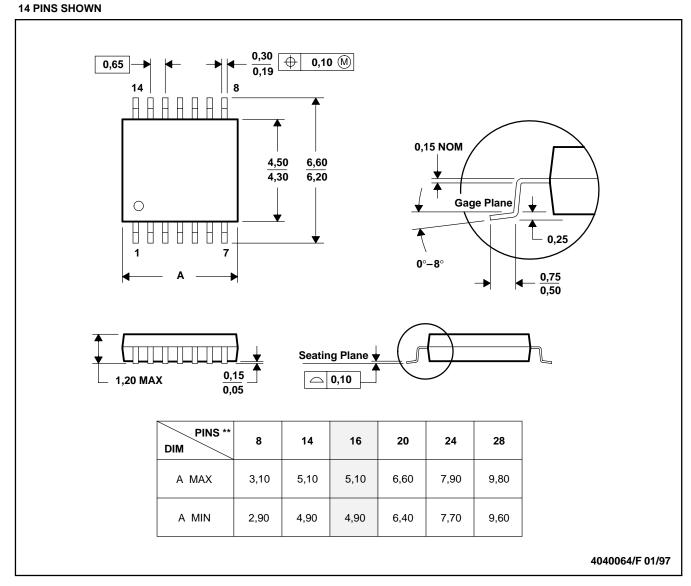


- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18, GDIP1-T20, and GDIP1-T22.

#### **MECHANICAL INFORMATION**

#### PW (R-PDSO-G\*\*)

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

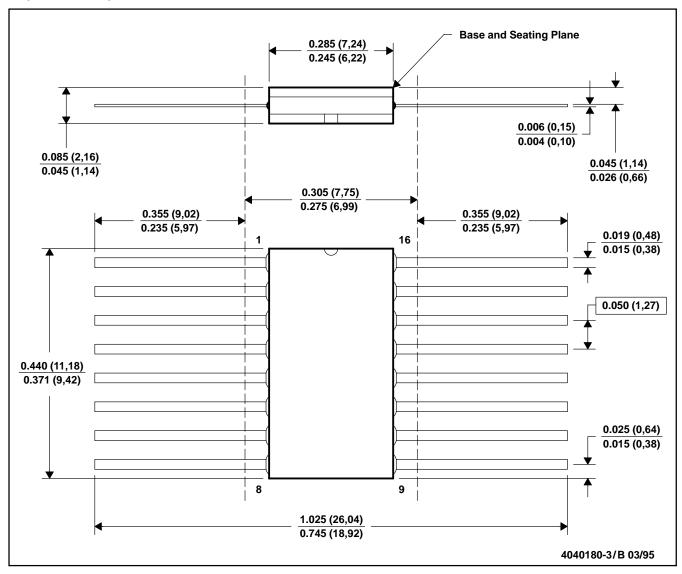
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

#### **MECHANICAL INFORMATION**

#### W (R-GDFP-F16)

#### **CERAMIC DUAL FLATPACK**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL-STD-1835 GDFP1-F16 and JEDEC MO-092AC

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